



Features

- Surface Mount Package
- Glass Passivated Diode Construction
- Moisture Resistant Epoxy Case
- High surge forward current capability

Maximum Ratings

- Operating Temperature: -55°C to +150°C
- Storage Temperature: -55°C to +150°C

Catalog Number	Device Marking	Maximum Rccurrent Peak Reverse Voltage	Maximum RMS Voltage	Maximum DC Blocking Voltage
RMSB610	RMSB610	1000V	700V	1000V

Electrical Characteristics @ 25°C Unless Otherwise Specified

Average Forward Current	$I_{F(AV)}$	6A	
Peak Forward Surge Current	I_{FSM}	130A	8.3ms, half sine
Maximum Instantaneous Forward Voltage	V_F	1.1V	$I_F = 6.0 A;$ $T_A = 25\text{ }^\circ C$
Maximum DC reverse current at Rated DC Blocking Voltage	I_R	5 μA 100 μA	$T_A = 25\text{ }^\circ C$ $T_A = 125\text{ }^\circ C$
Maximum Reverse Recovery Time	T_{RR}	500ns	
$I^2 t$ Rating for fusing (1ms < t < 8.3ms)	$I^2 t$	60 A ² sec	

MSB

DIM	INC HES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	0.276	0.291	7.000	7.400	
B	0.256	0.272	6.500	6.900	
C	0.047	0.063	1.200	1.600	
D	0.319	0.335	8.100	8.500	
E	0.193	0.209	4.900	5.300	
F	0.035	0.049	0.900	1.250	
G	0.110	0.126	2.800	3.200	
H	0.008	0.016	0.200	0.400	

CHIP DIMENSION Square SIZE DESIGN



FIG.1-MAXIMUM FORWARD SURNGE CURRENT

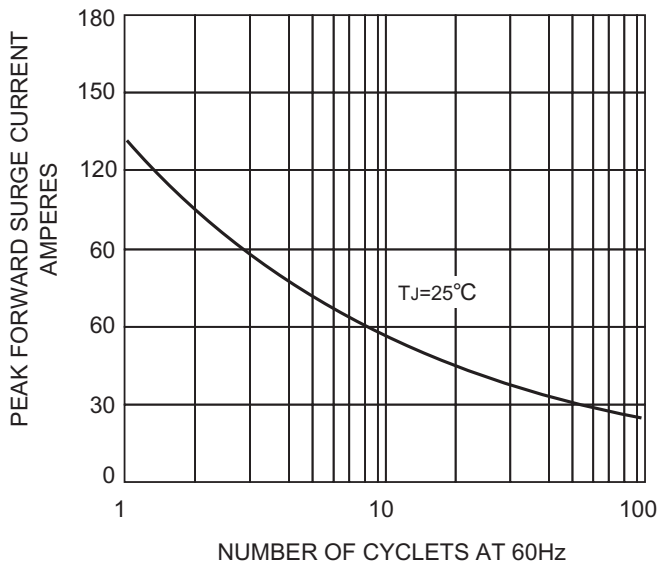


FIG.2-FORWARD CURRENT DERATING CURVE

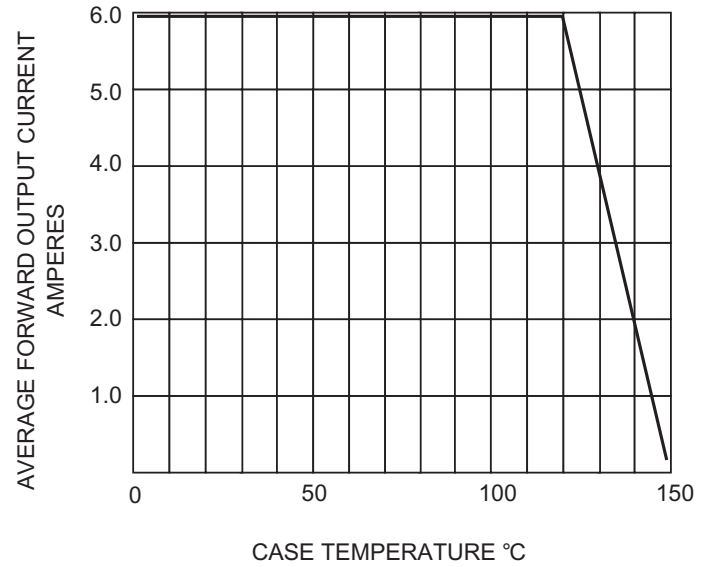


FIG.3-TYPICAL FORWARD CHARACTERISTICS

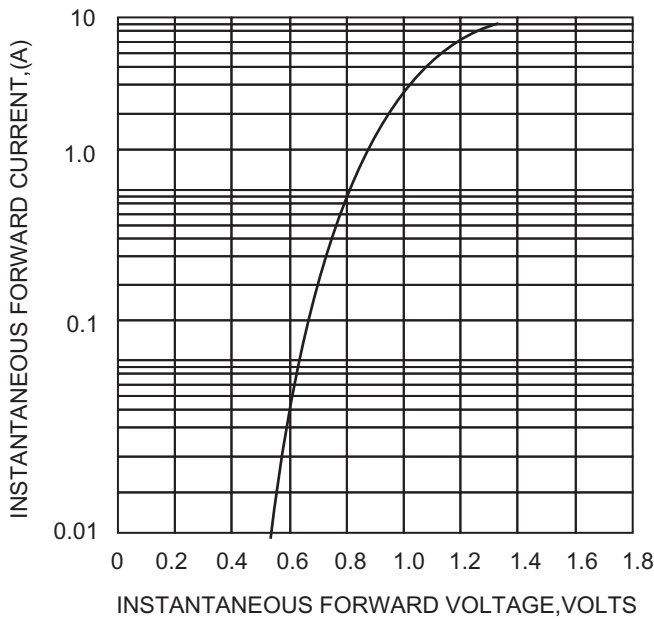
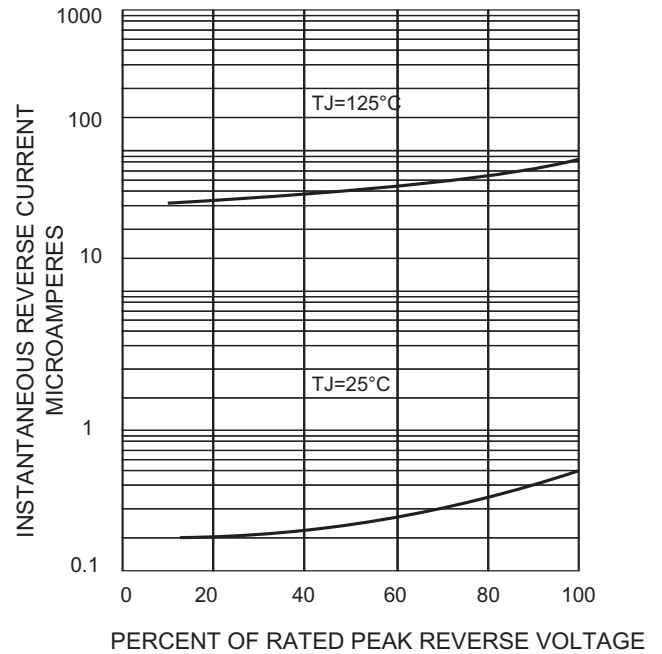
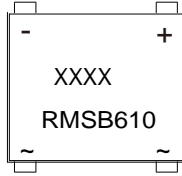


FIG.4 -TYPICAL REVERSE CHARACTERISTICS





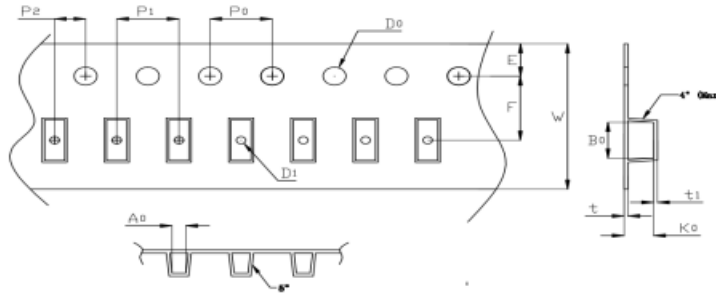
MARKING INFORMATION



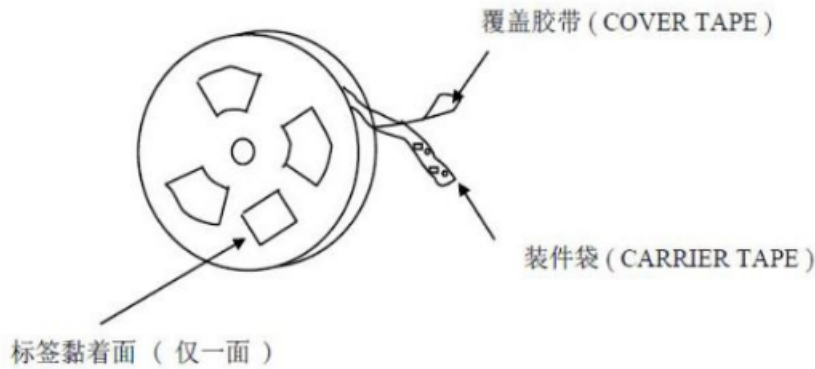
XXXX = Date Code Marking
MSB610 = Marking Code

PACKING REQUIRMENTS

- PS black anti-static carrier tape packing.



Specifications	Carrier tape type	Ao	Bo	Ko	Po	W	t1	Explain
MSB	Anti-static	7.0±0.10	8.7±0.10	1.65±0.10	4.00±0.10	16.0±0.30	0.28±0.05	



DEVICE TYPE	Tape width	13" Reel		
		Q'TY/REEL (pcs)	BOX/CAR TOON	Q'TY/REEL (pcs)
MSB	16mm	3000	6000	60000